


Low-Power SRAM Design using Low-Voltage and Low-Swing Techniques

**Master thesis presentation
February 13, 2002**

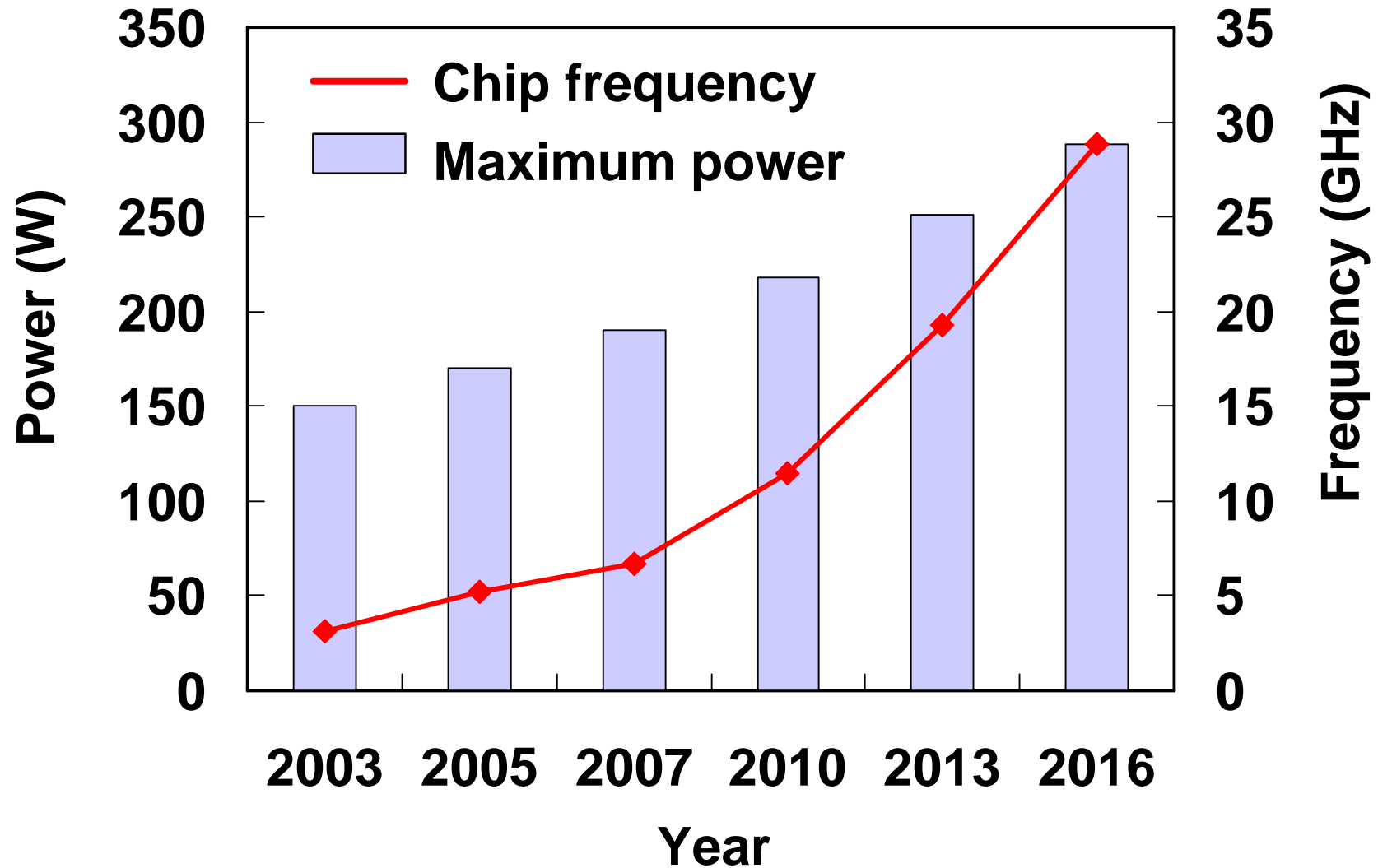
**Department of Electronic Engineering,
Graduate School of Engineering,
the University of Tokyo**

Sadaaki Hattori

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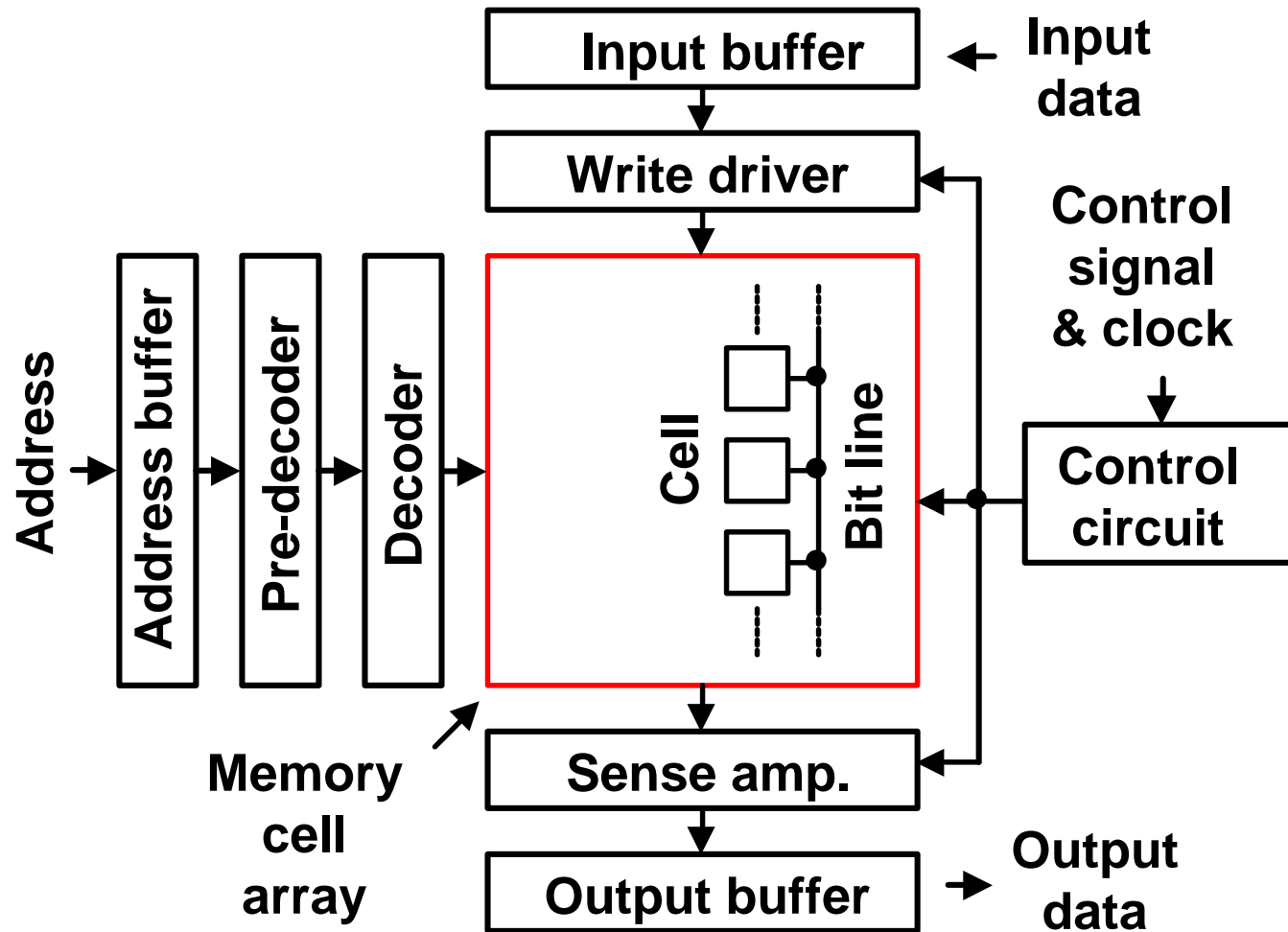
- 
- 1. Background**
 - 2. Write power saving scheme**
 - 3. Power saving scheme for peripheral circuits and decoders**
 - 4. Power saving scheme for register file**
 - 5. Summary**

Power crisis in VLSI



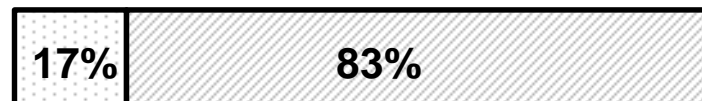
(ITRS: International Technology Roadmap for Semiconductors 2001)

SRAM Architecture



4Mbit SRAM
Write power

Peripheral Bit line (256 bit)

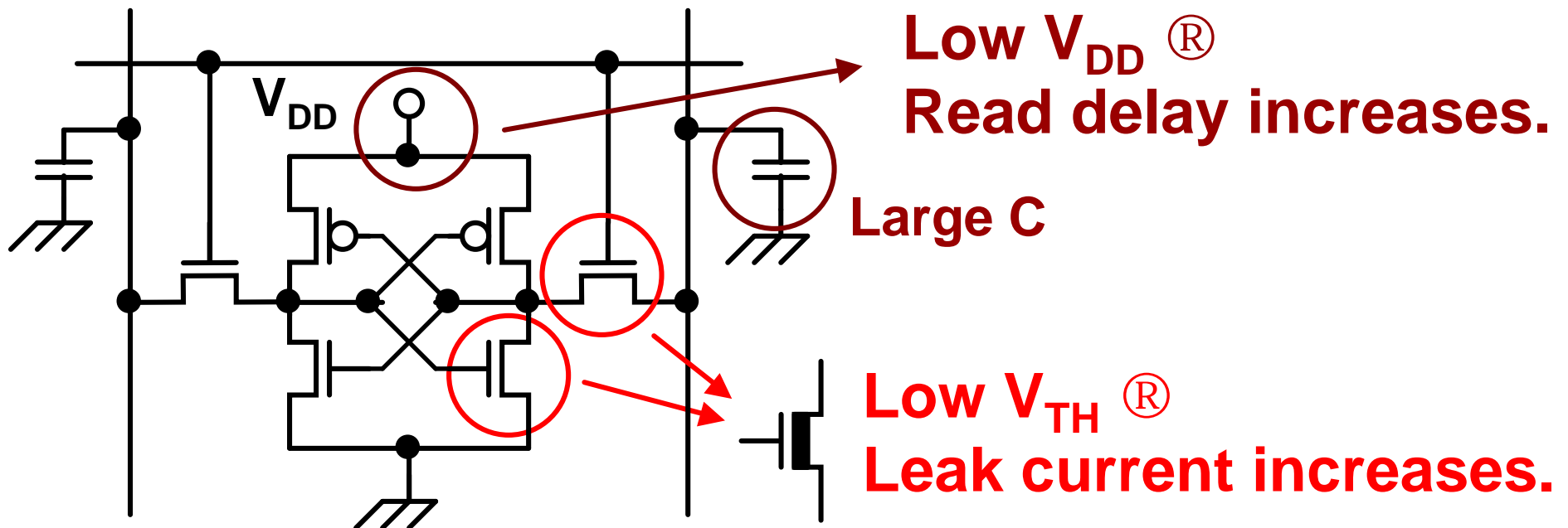


$$P = f_{\text{CLK}} C_L V_{\text{DD}}^2$$

f_{CLK} : clock frequency C_L : load capacitance
 V_{DD} : supply voltage

Lowering V_{DD} is the best solution to power reduction in logic circuits.

Lowering V_{DD} of SRAM cell is difficult.



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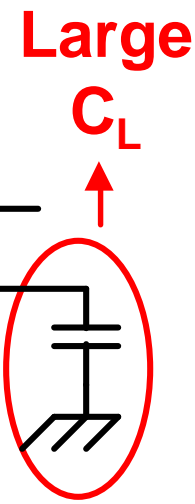
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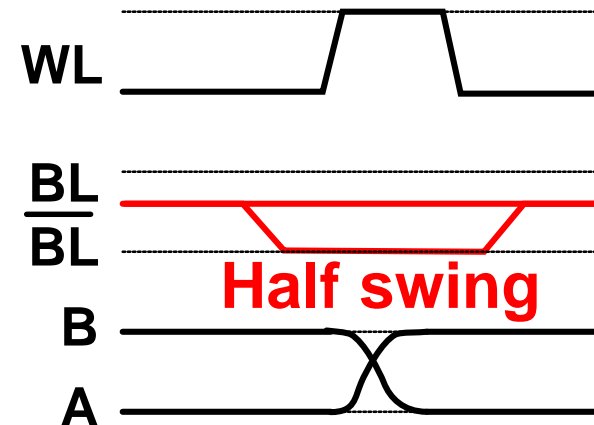
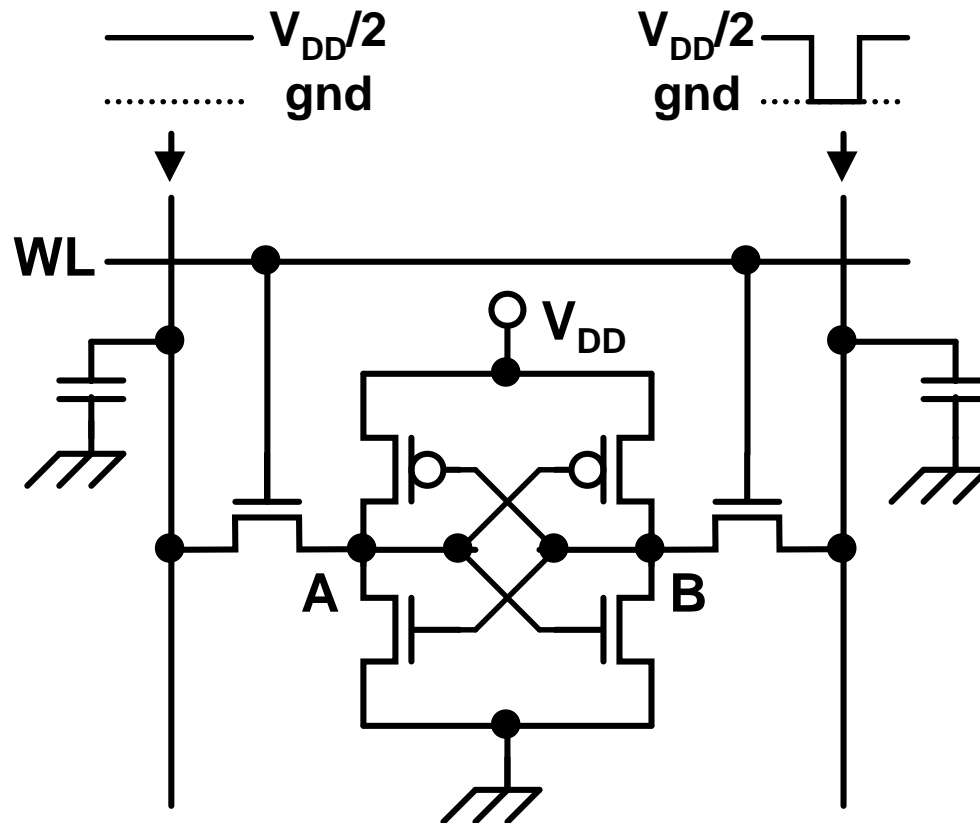


**Full swing of bit-line
dissipates large power
in write cycles.**

$$P = f_{CLK} C_L V_{DD}^2$$

$$P = f_{CLK} C_L V_{DD}^2$$

SRAM cell using half-swing bit-line



- Further power reduction is difficult because cell node potential cannot be inverted at lower swing.

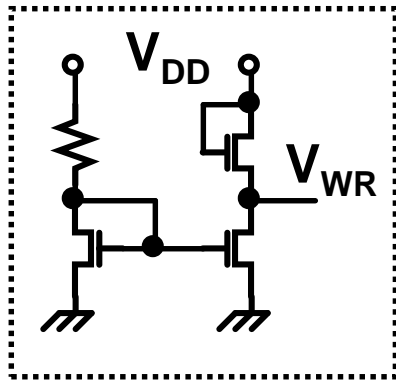
- Additional power in alternate write and read cycles.

$$P = f_{\text{CLK}} C_L (1/4) V_{\text{DD}}^2$$

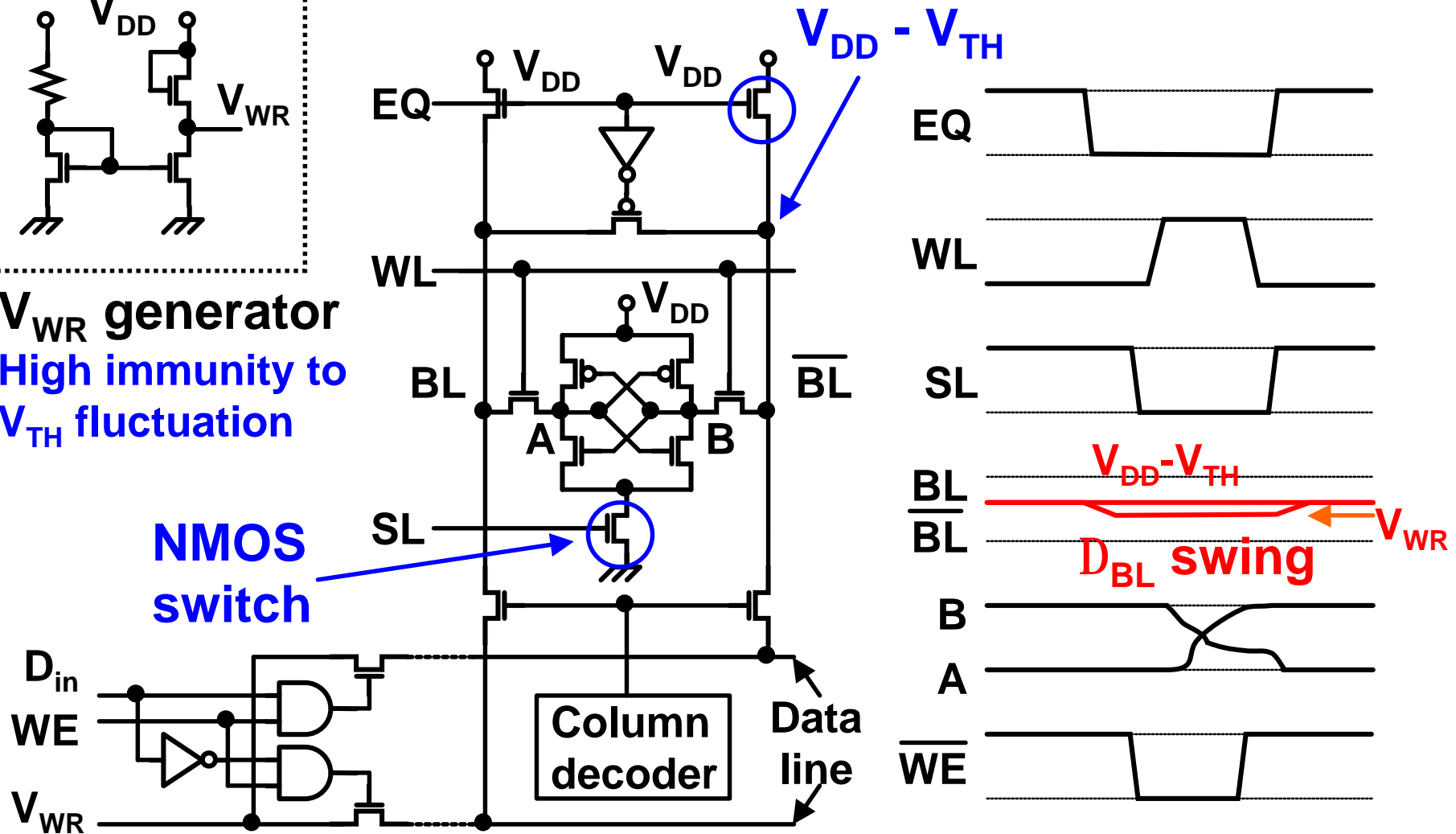
with charge recycling

(Mark A. Horowitz et al.,
“Low-power SRAM Design Using Half-Swing Pulse-mode Techniques”,
IEEE Journal of SSC, Vol. 33, pp. 1659-1671, Nov., 1998)

Sense-amplifying cell (SAC) scheme

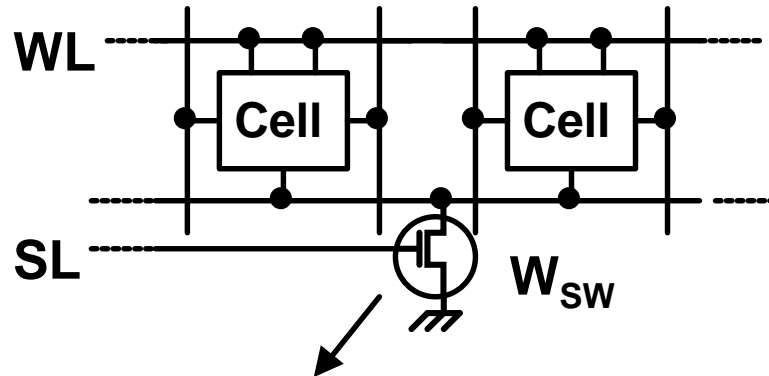


V_{WR} generator
High immunity to V_{TH} fluctuation



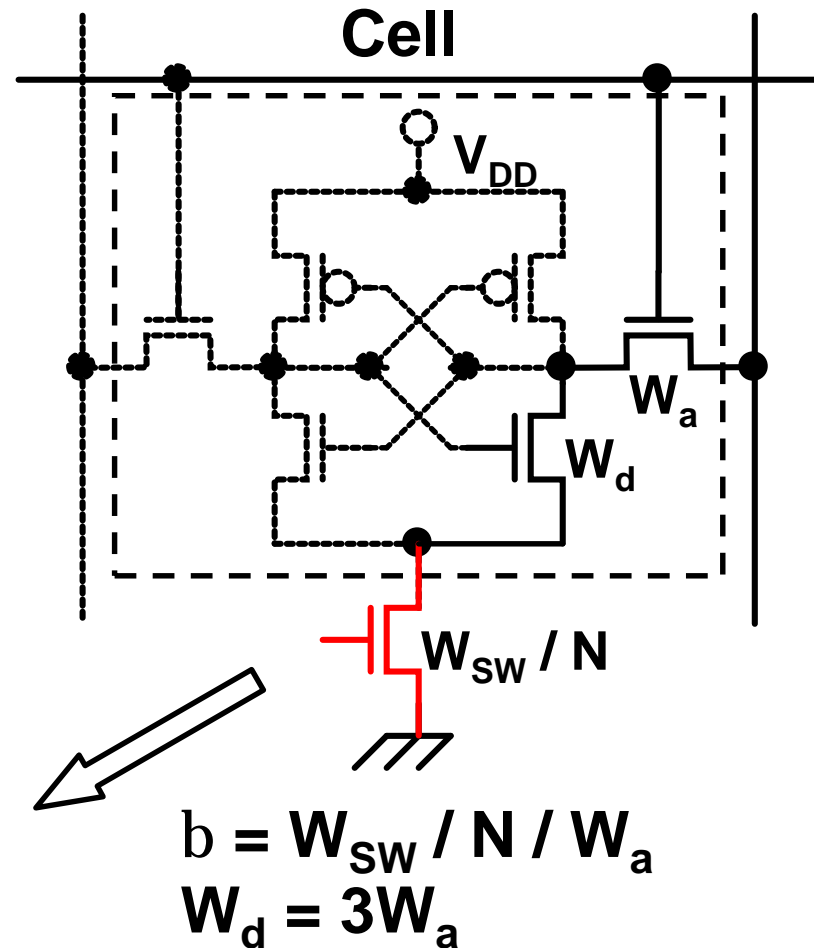
$$P = f_{CLK} C_L D V_{BL}^2$$

Design Considerations

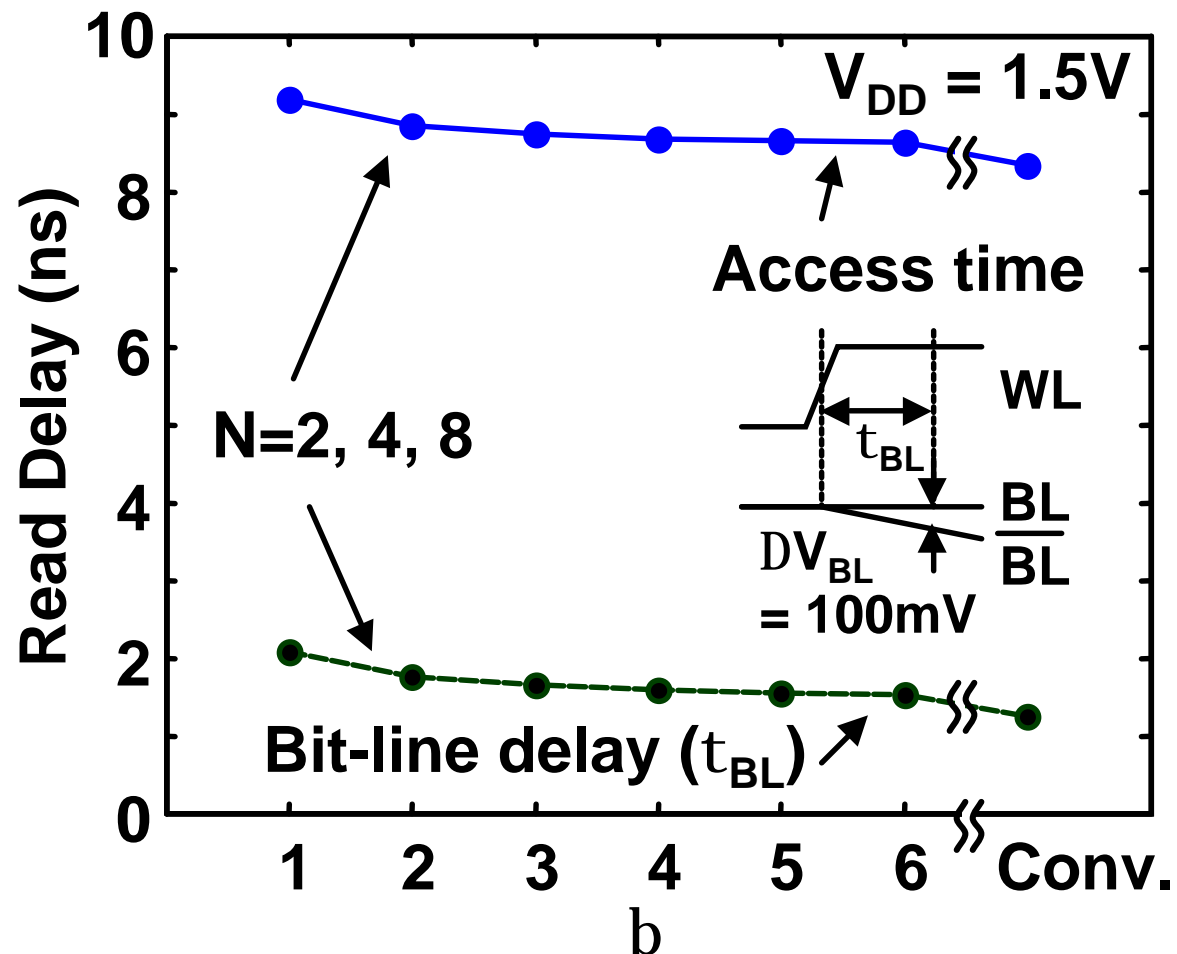


NMOS switch is shared
by N cells ($N = 2, 4, 8$)

- Read access time -
- Noise margin -
- Area overhead -

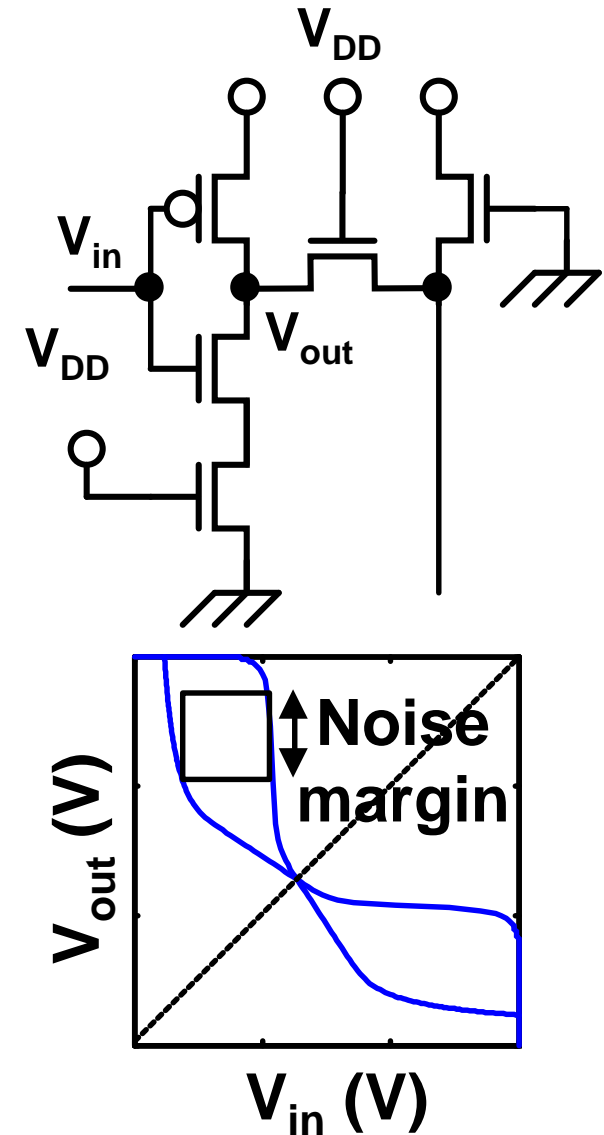
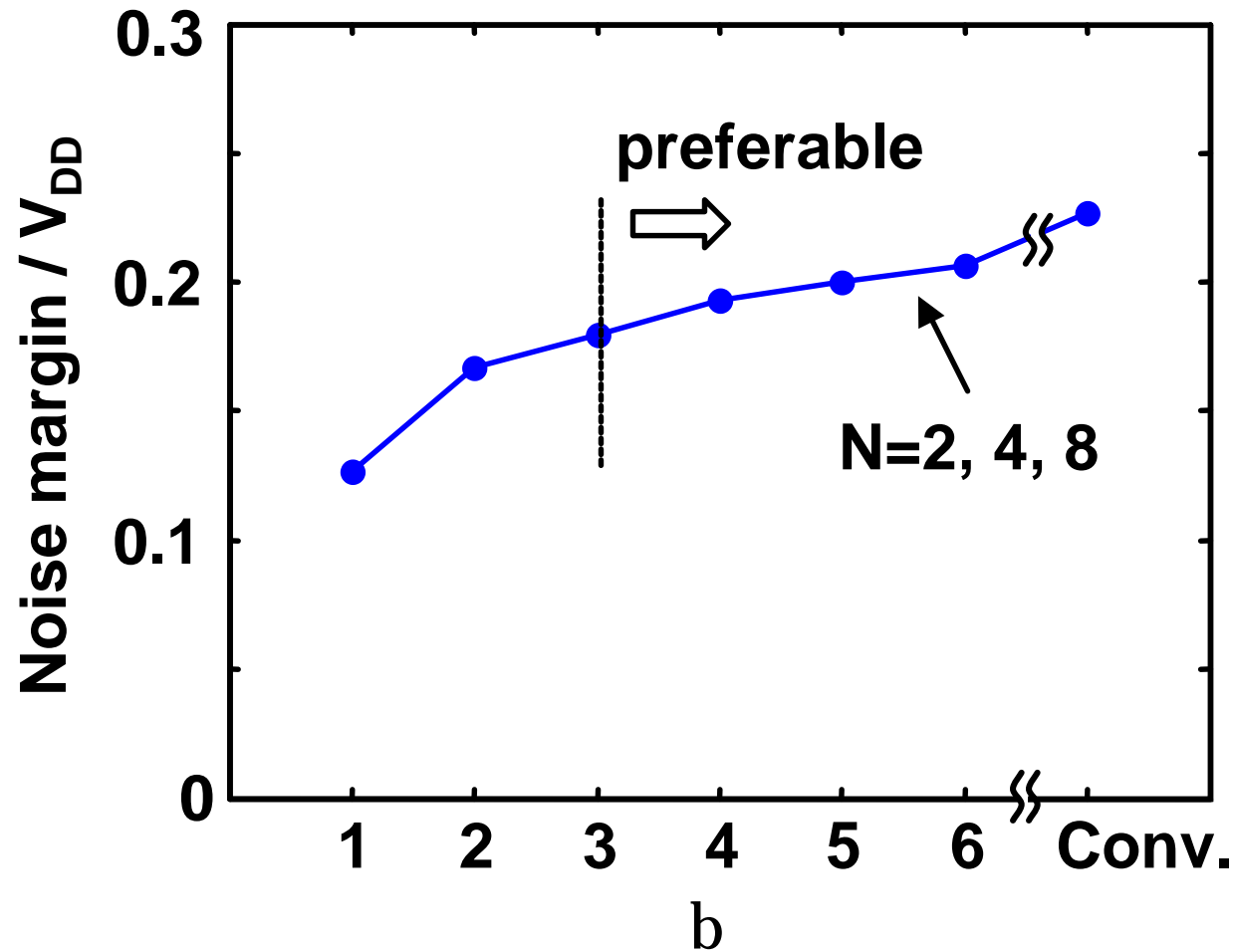


Read delay

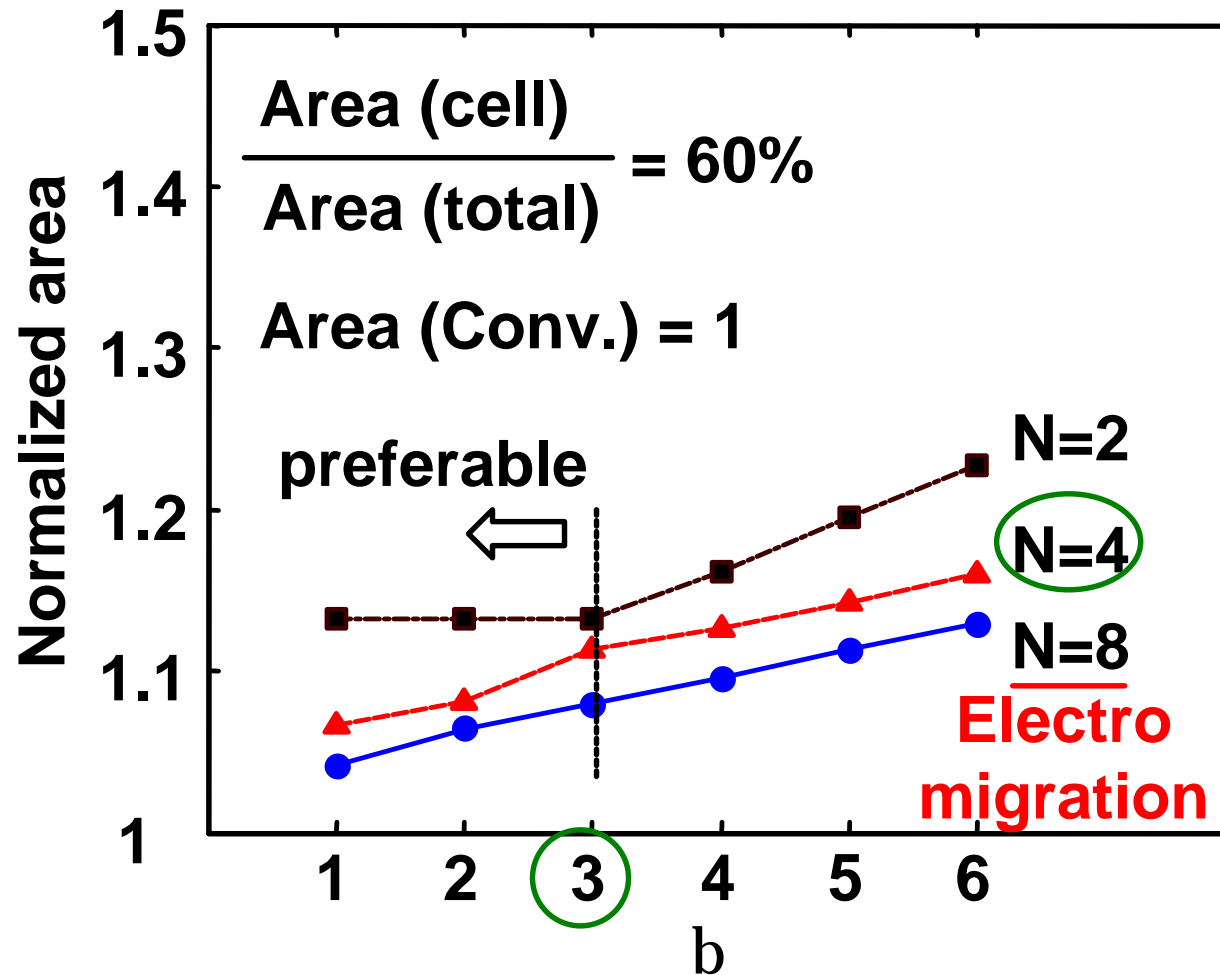


Addressing time: 4.0 ns (calculated)
Data output time: 3.1 ns (calculated)

Noise margin analysis

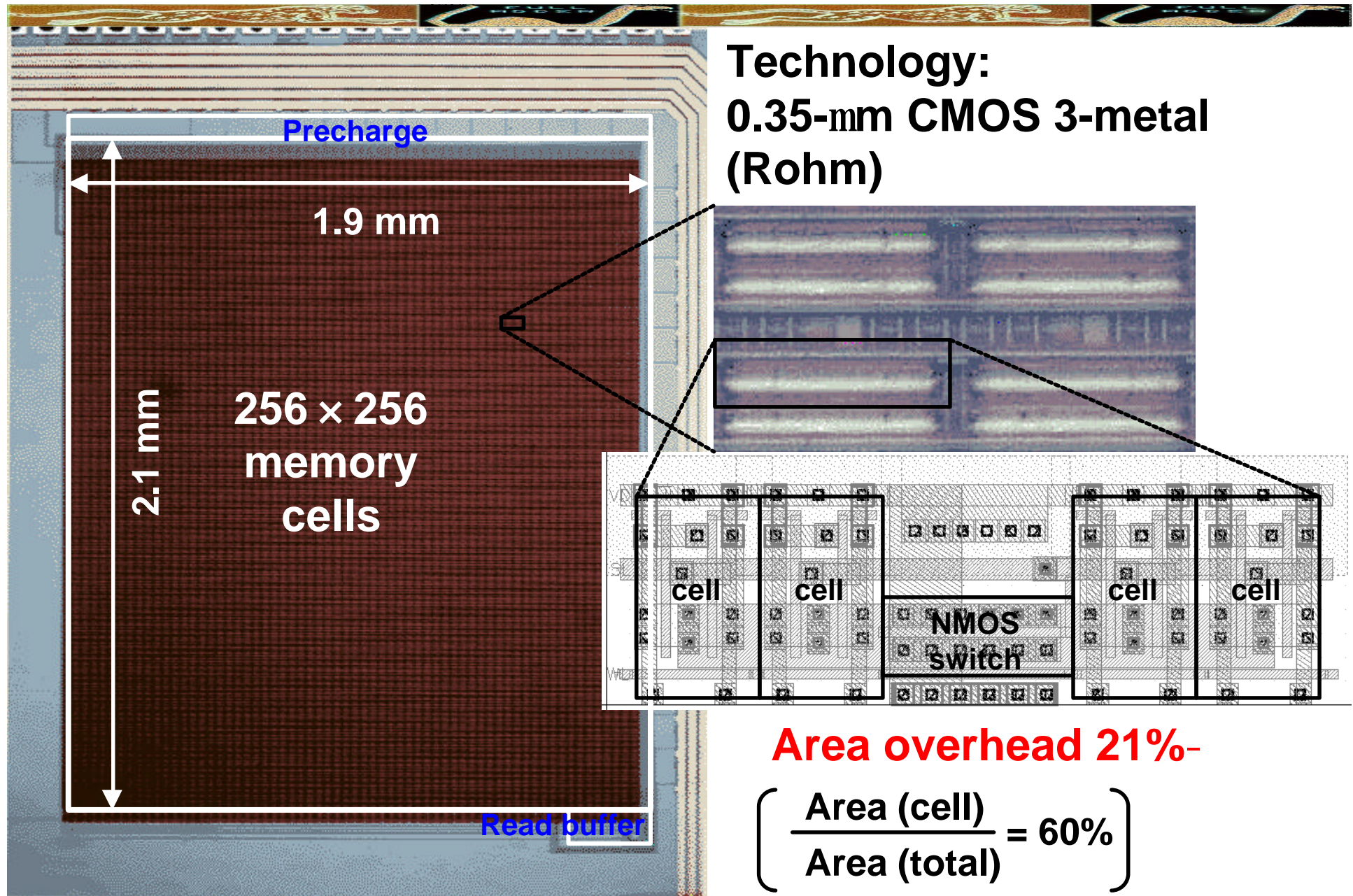


Area overhead

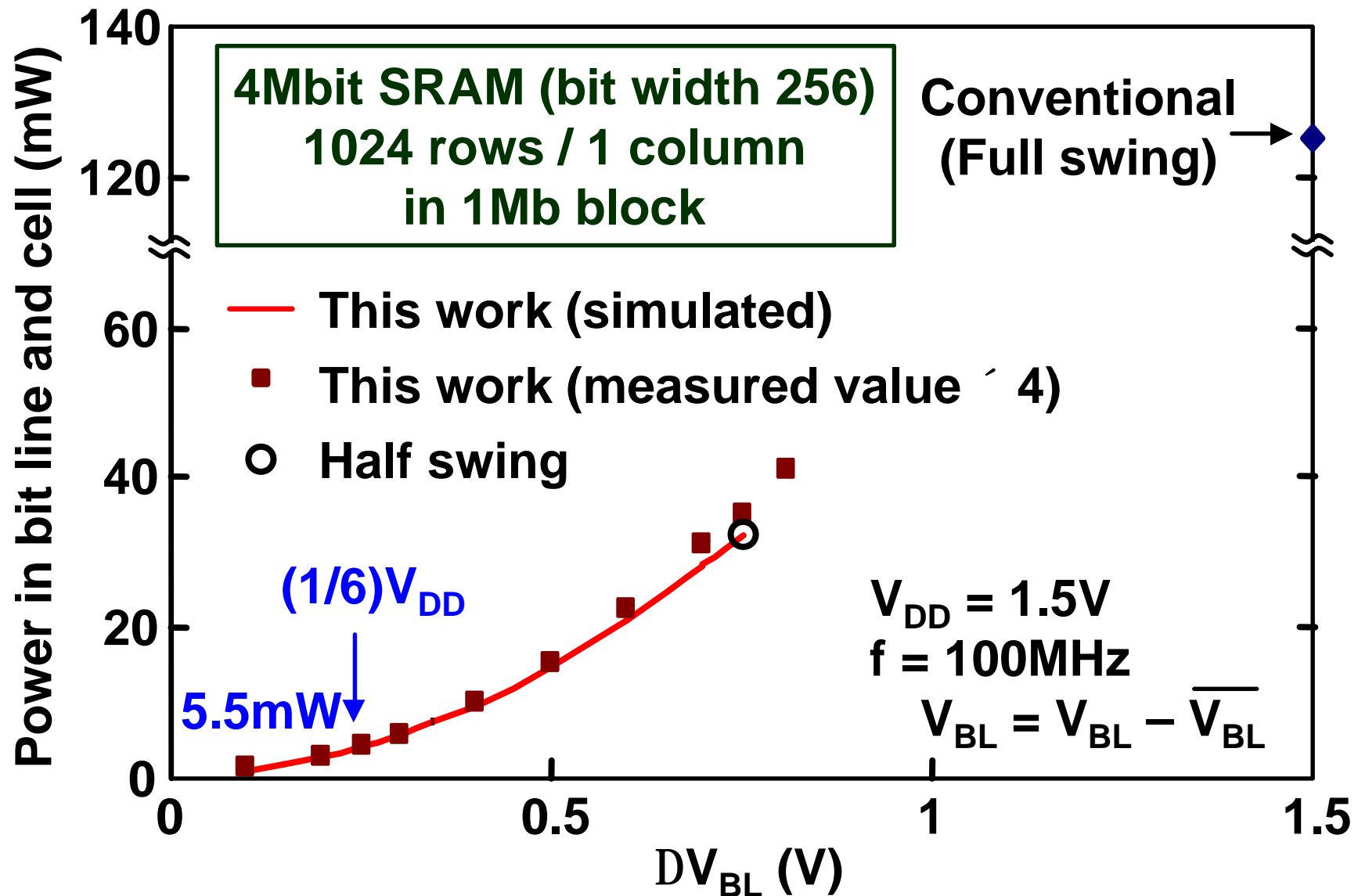


■ Read access time: 5%-
 ■ Noise margin: $0.05V_{DD}$ -
 ■ Area overhead: 11%-
 b=3, N=4

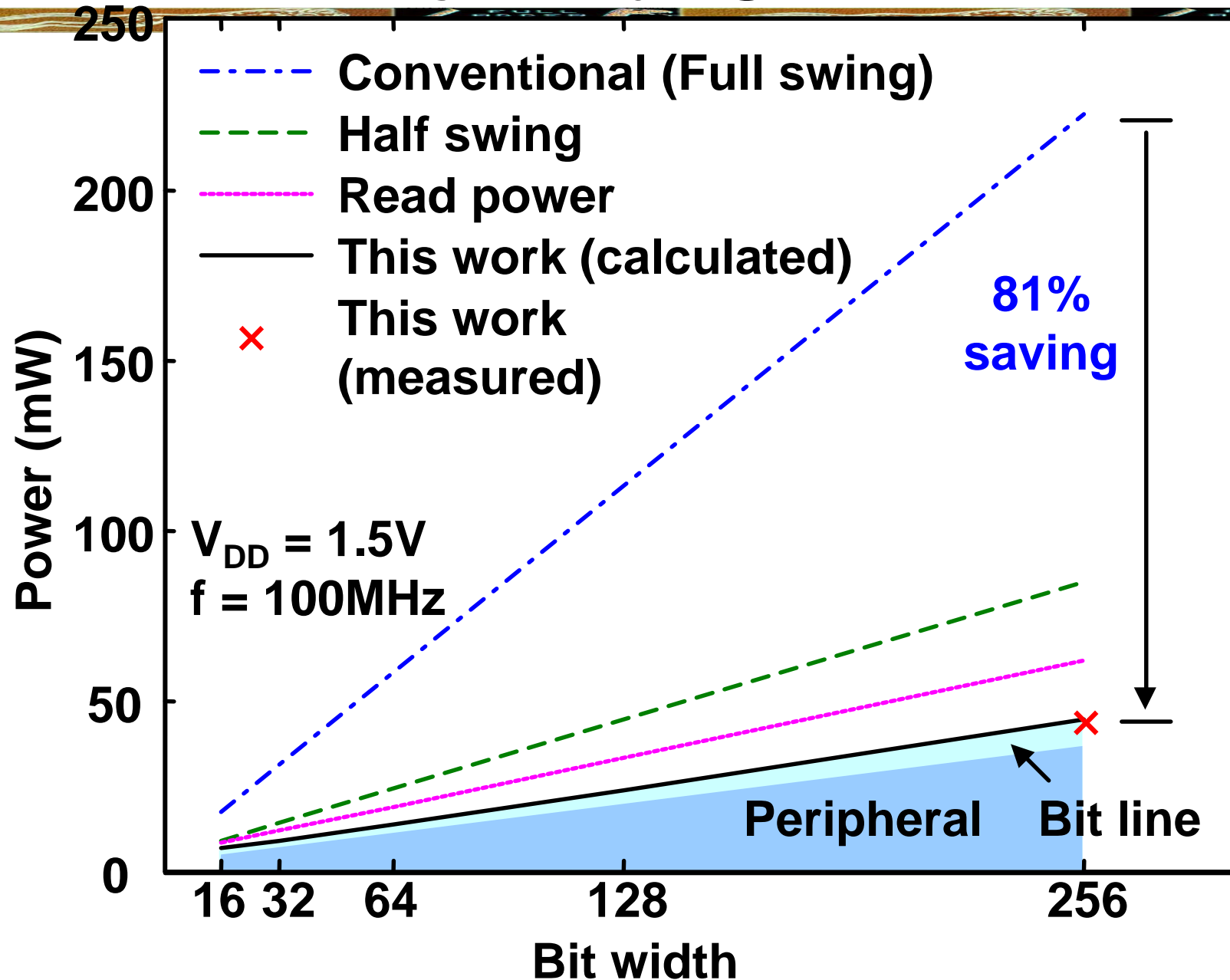
Microphotograph of 1st SRAM test chip



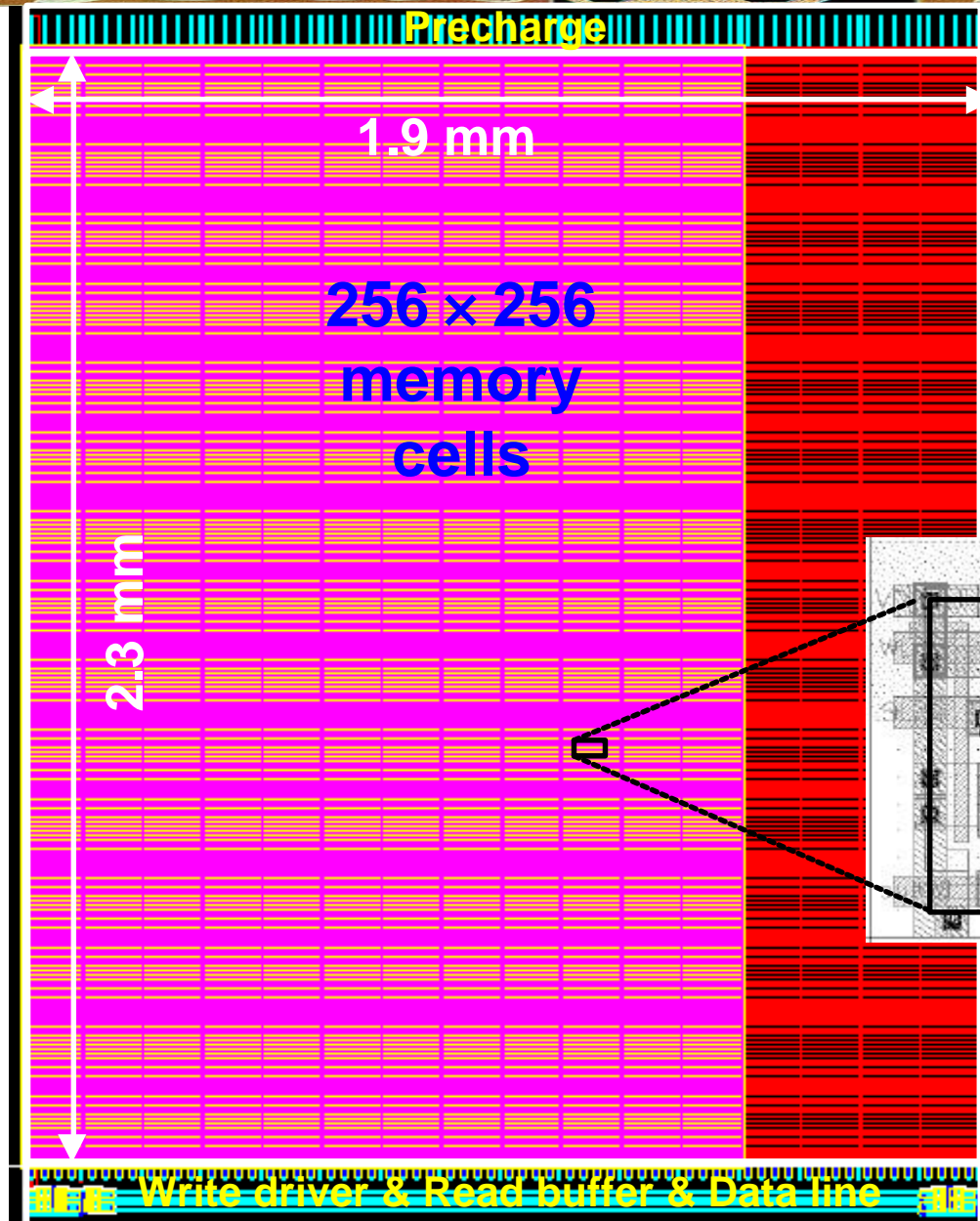
Write power consumption in memory cell arrays



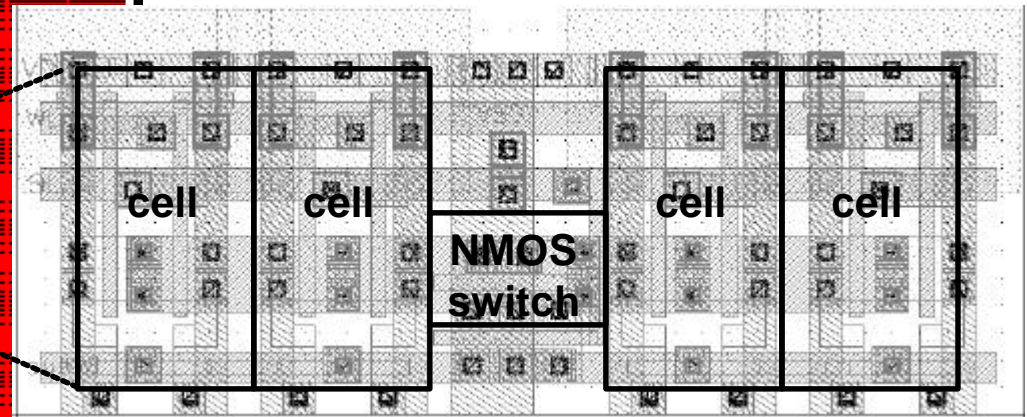
Total write power consumption of 4Mbit SRAM



Layout of 2nd SRAM test chip



Technology:
0.35- μ m CMOS 3-metal
(Rohm)



Area overhead 11%-

$$\left(\frac{\text{Area (cell)}}{\text{Area (total)}} = 60\% \right)$$

Summary of SAC scheme



- ◆ **Sense-amplifying cell (SAC) scheme saves total write power of 4Mbit SRAM by 81% at bit width of 256.**
- ◆ **Test chip is fabricated at $b=3$, $N=4$.**
- ◆ **Read access time increases by 5%.**
- ◆ **Noise margin increases by $0.05V_{DD}$.**
- ◆ **Total area increases by 11%.**

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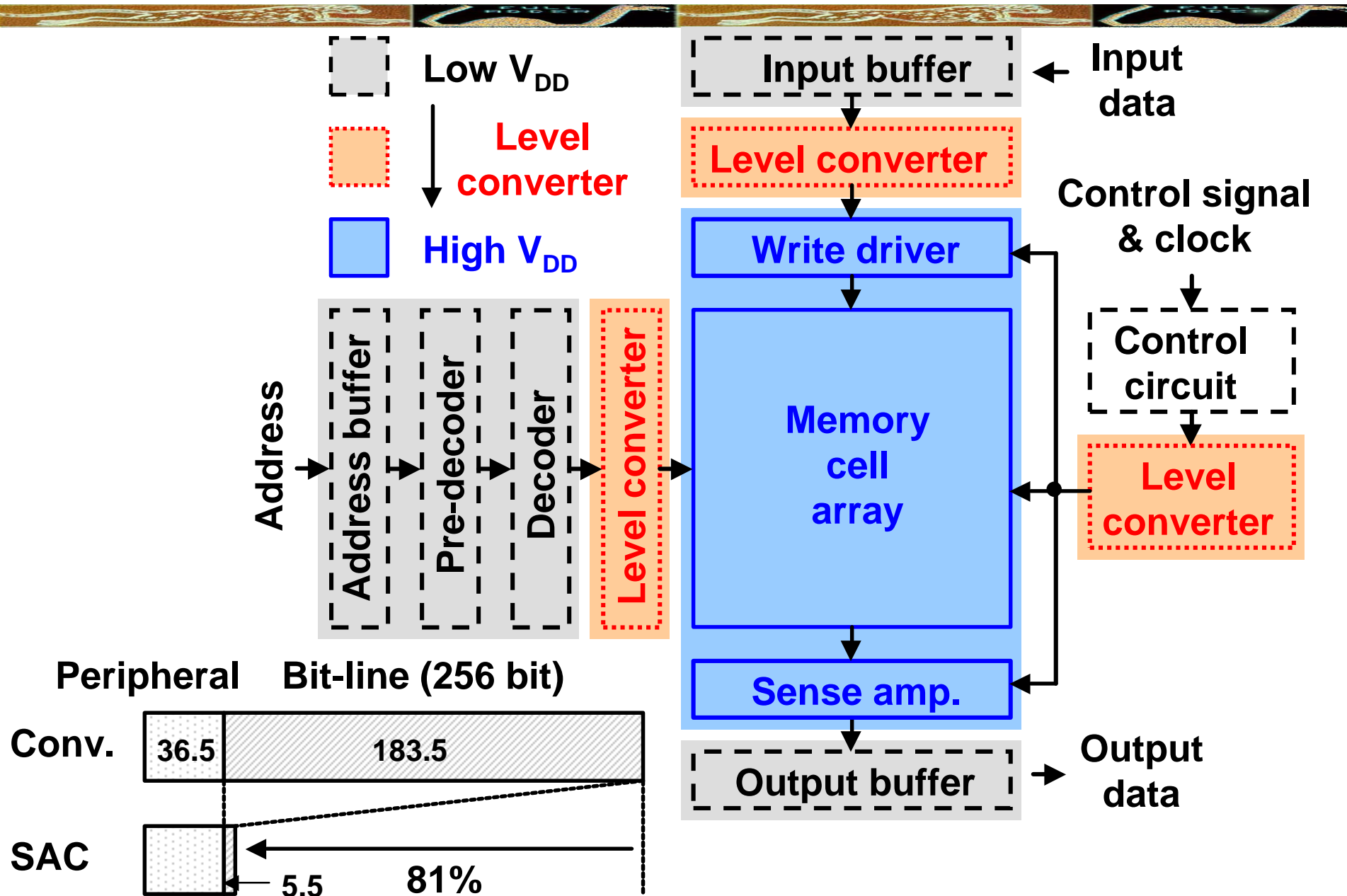
2. Write power saving scheme

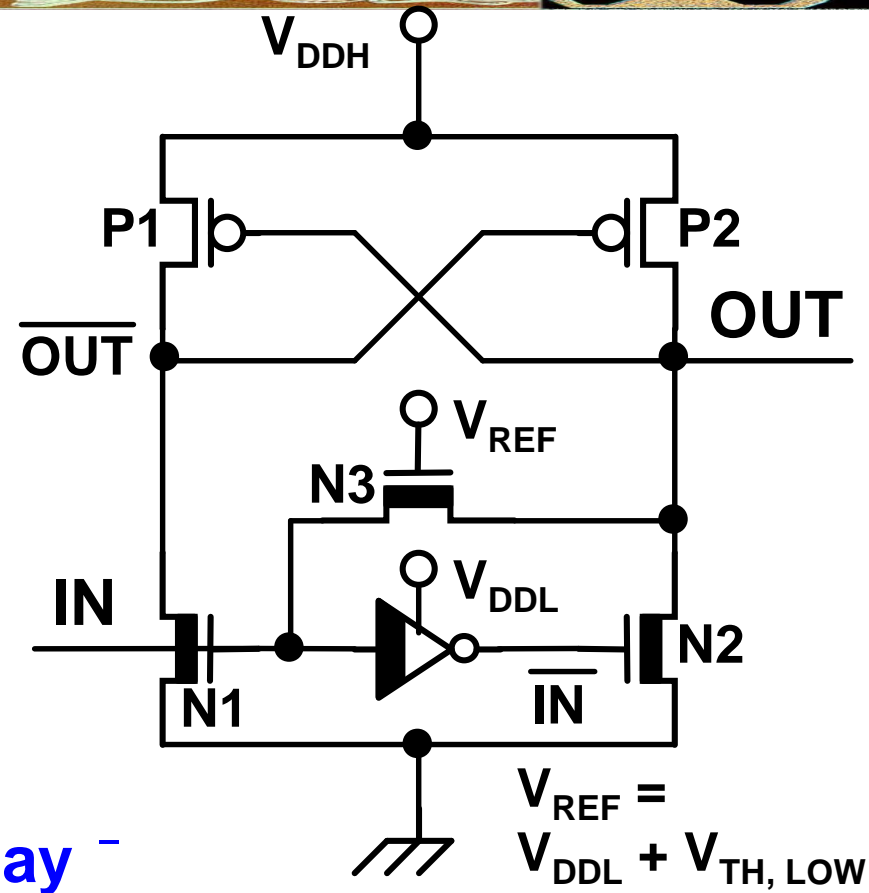
3. Power saving scheme for peripheral circuits and decoders

4. Power saving scheme for register file

5. Conclusion

Dual- V_{DD} SRAM architecture

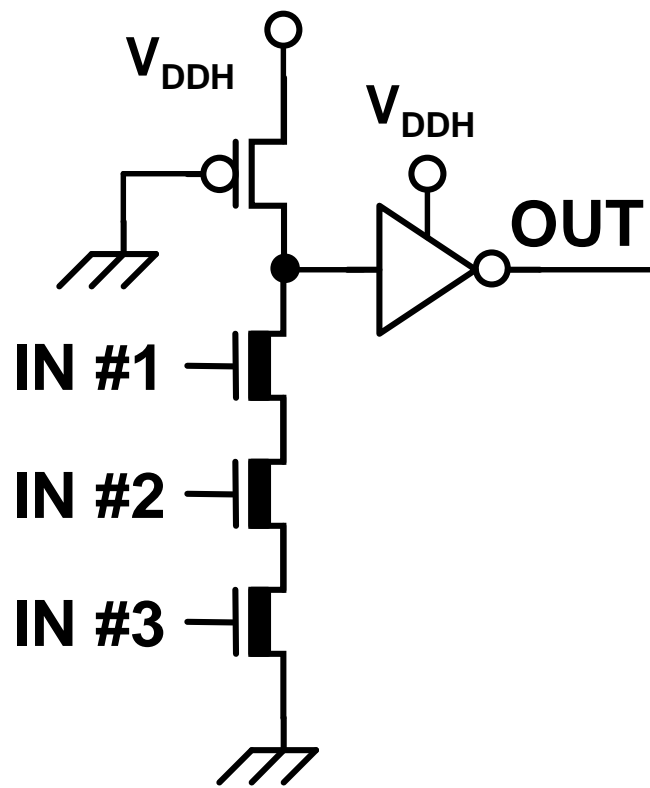




Proposed

Low immunity to V_{TH} fluctuation

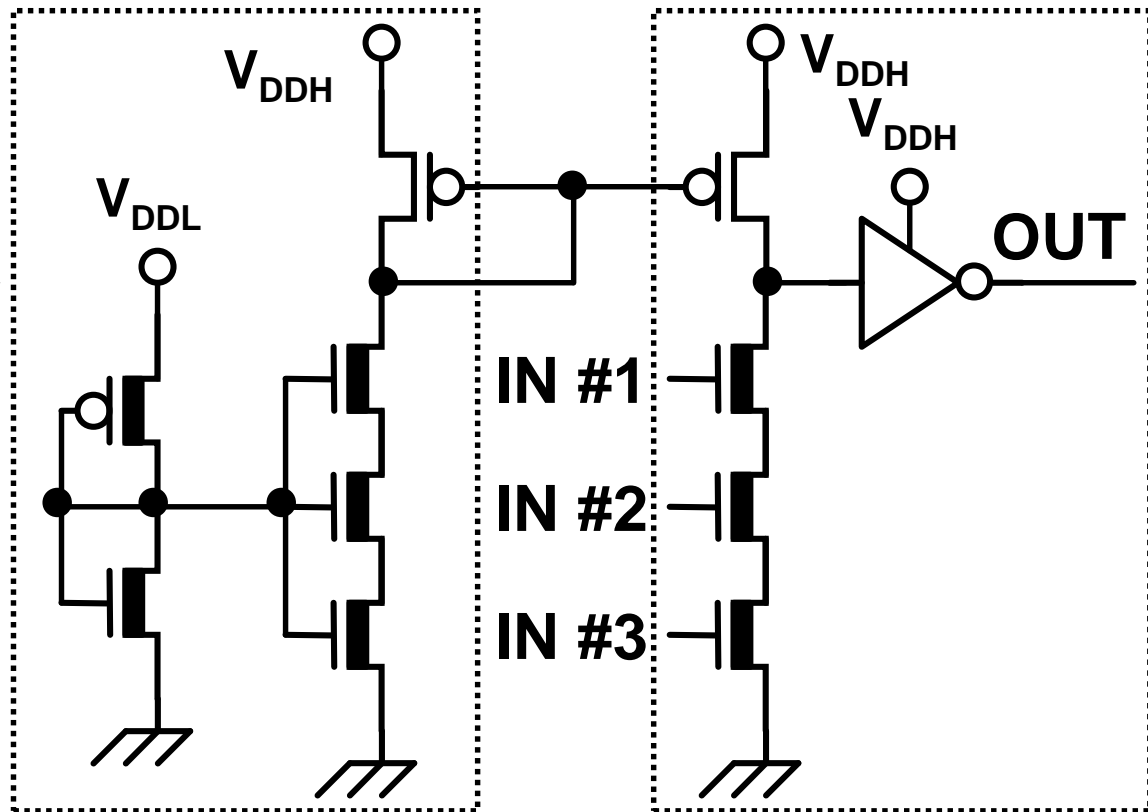
Proposed level converter



Pseudo NMOS

Fastest

Low immunity to V_{TH} fluctuation



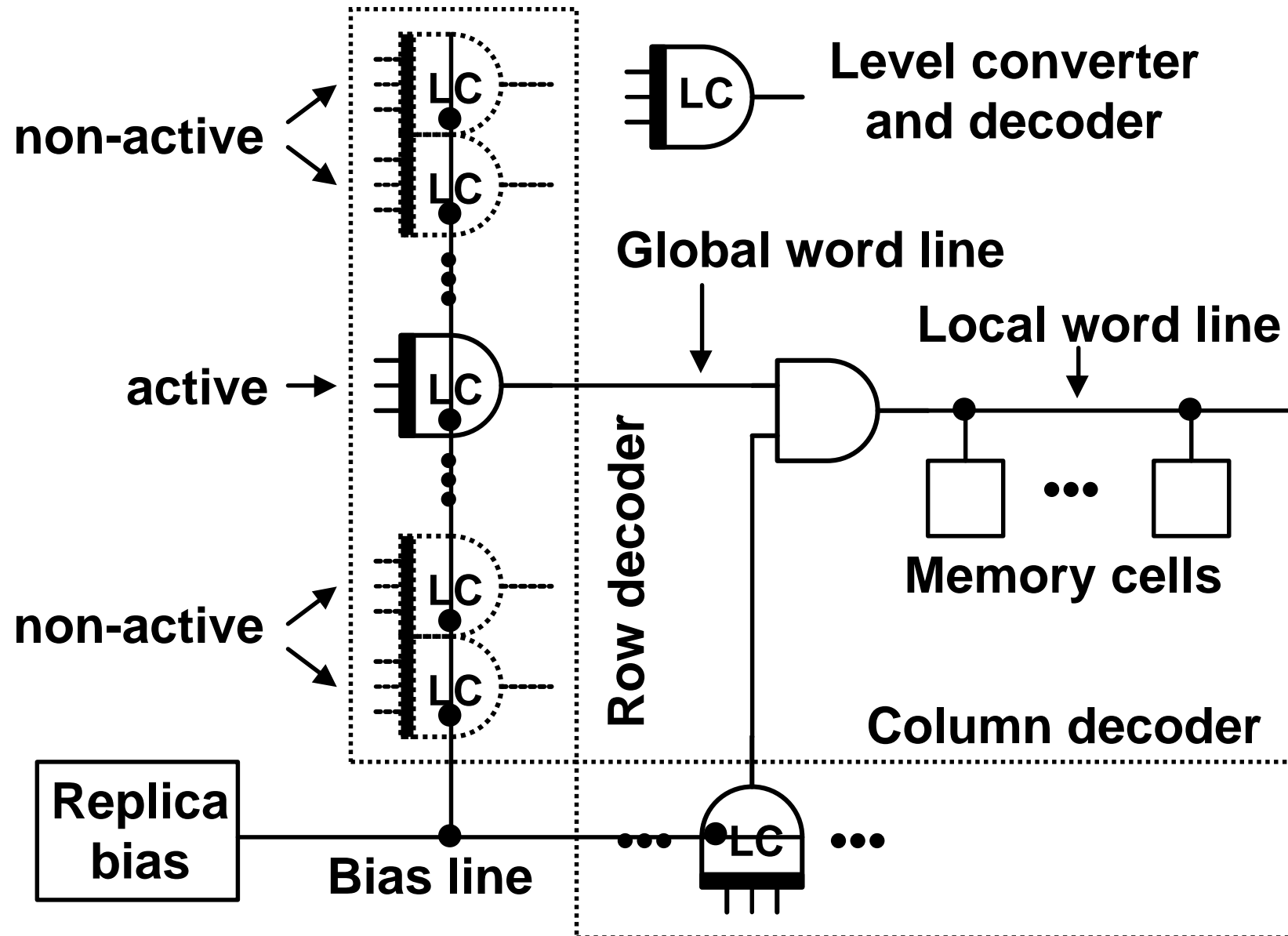
Replica bias

Replica-biased level converter

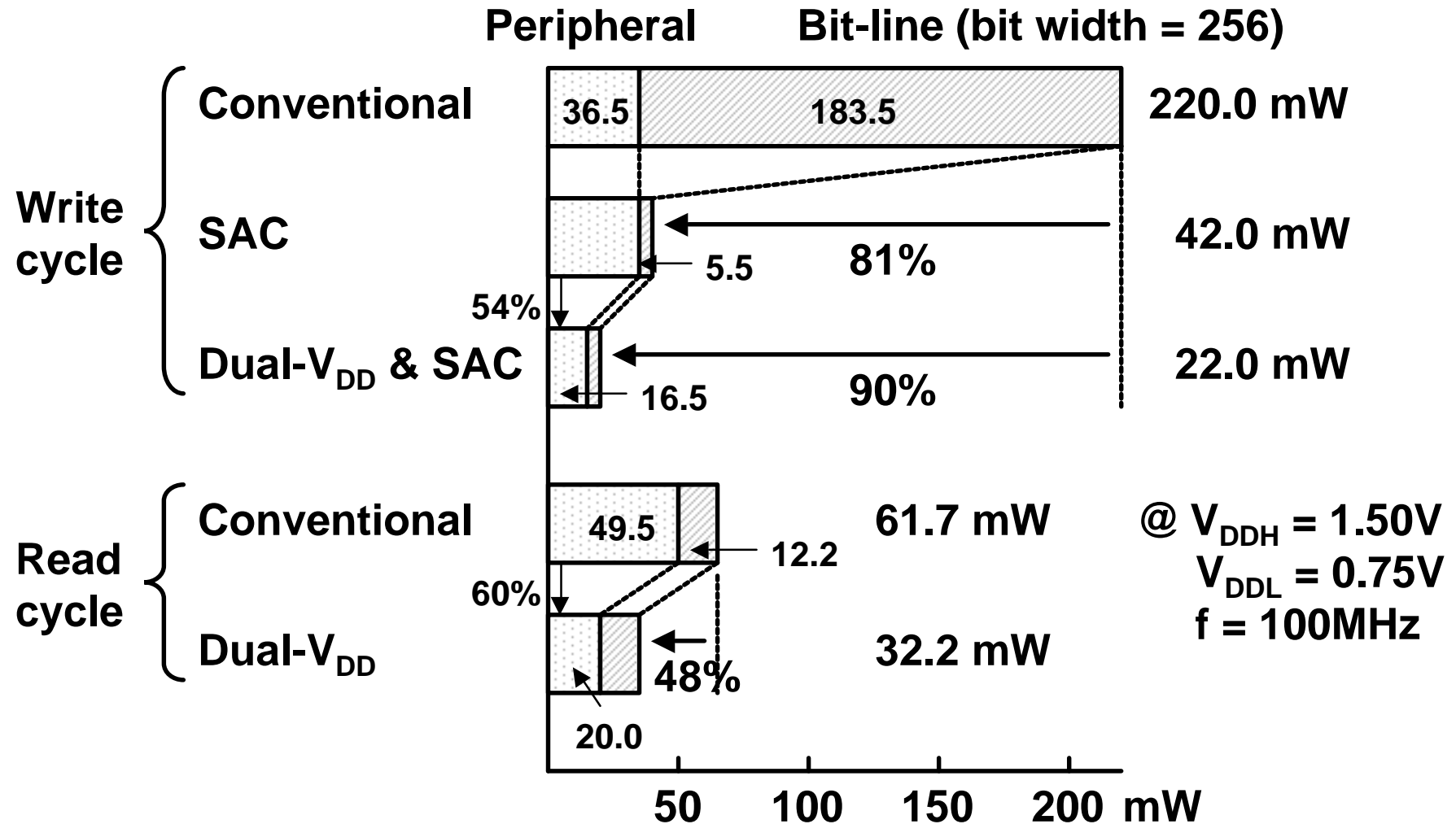
AND gate

High immunity to V_{TH} fluctuation

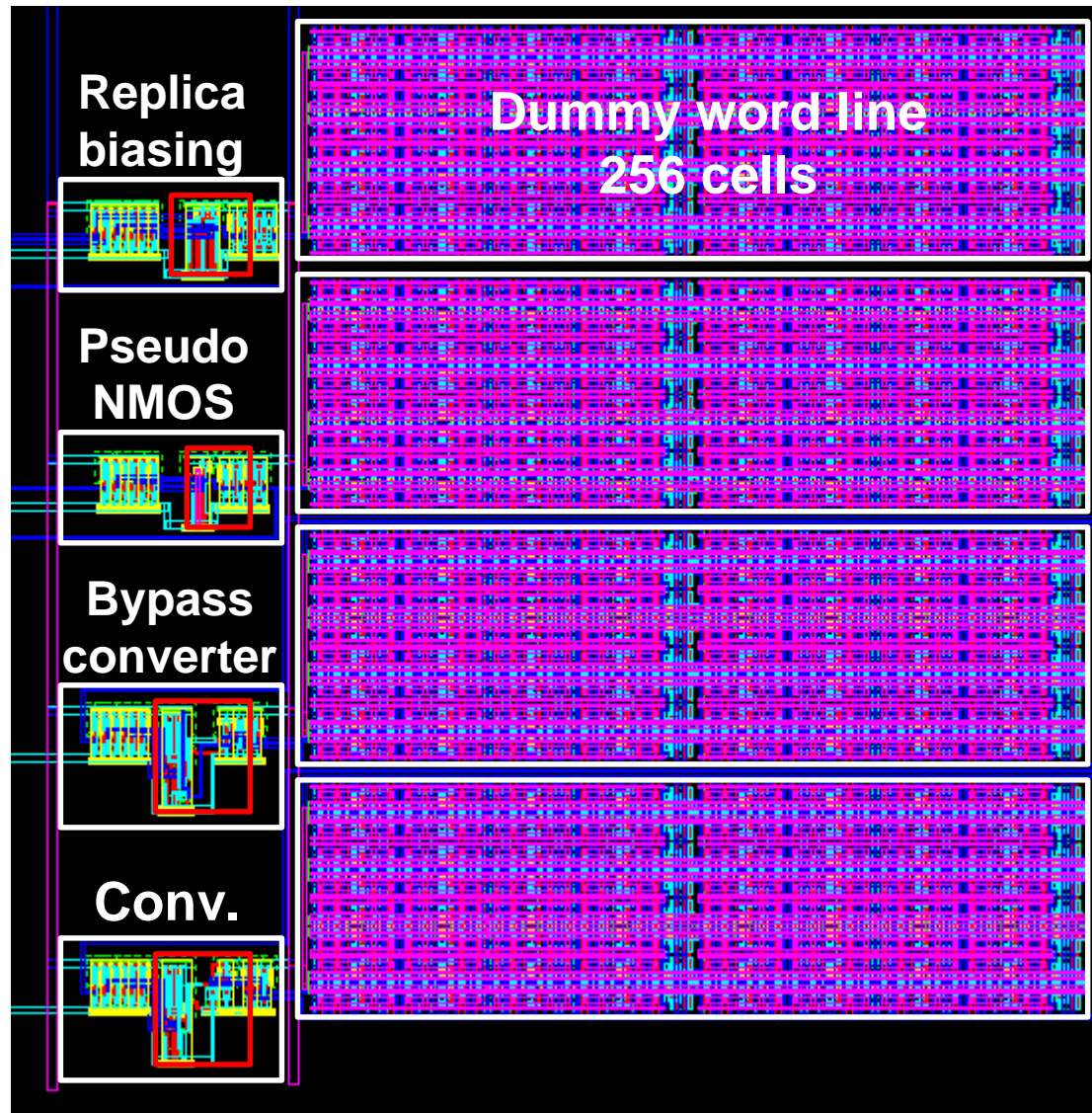
Level converter and decoder



Power consumption of 4Mbit SRAM

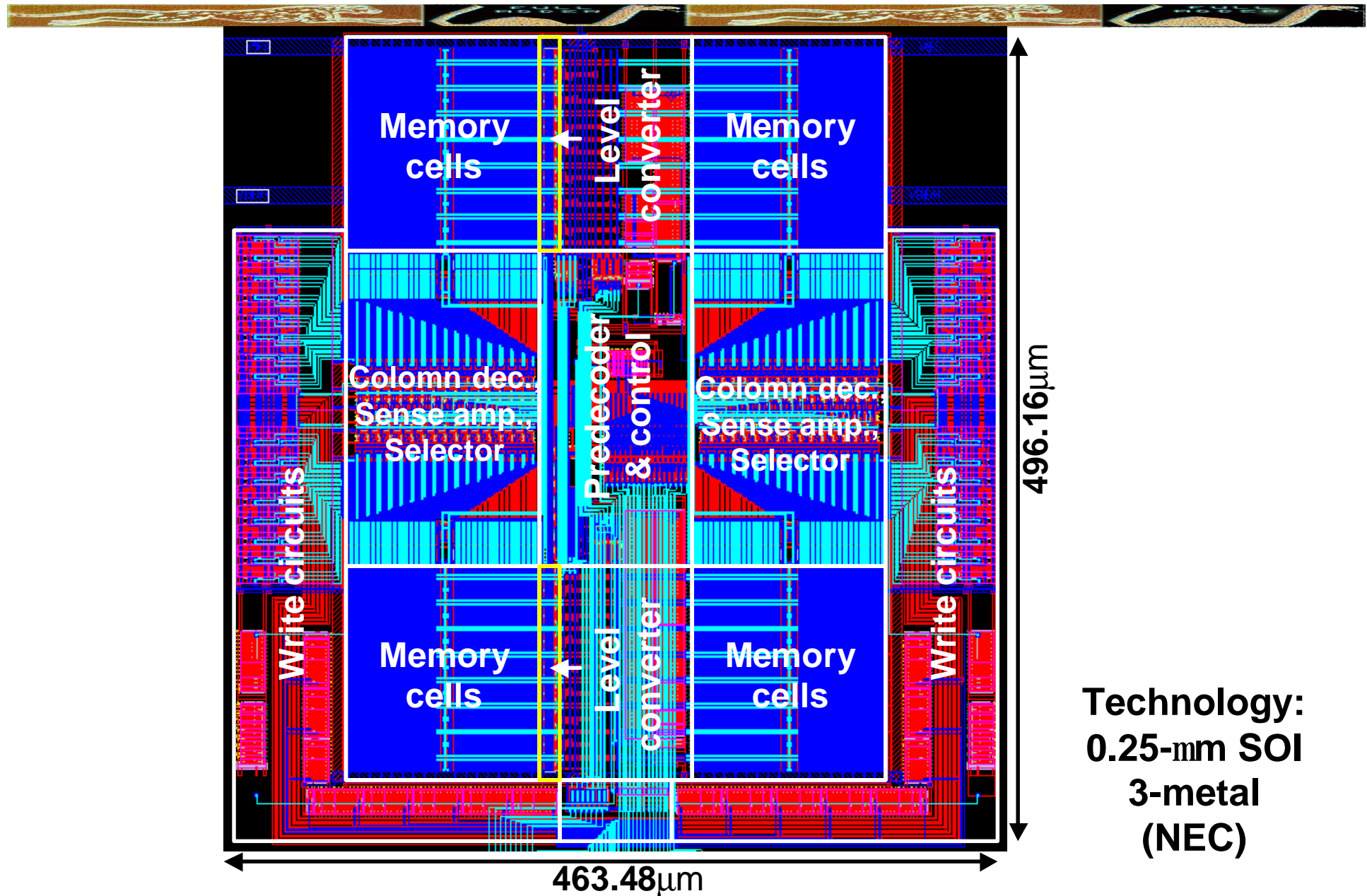


Layout of level converters



Technology:
0.35- μ m CMOS
3-metal
(Rohm)

Layout of 2Kbit SRAM with level converter

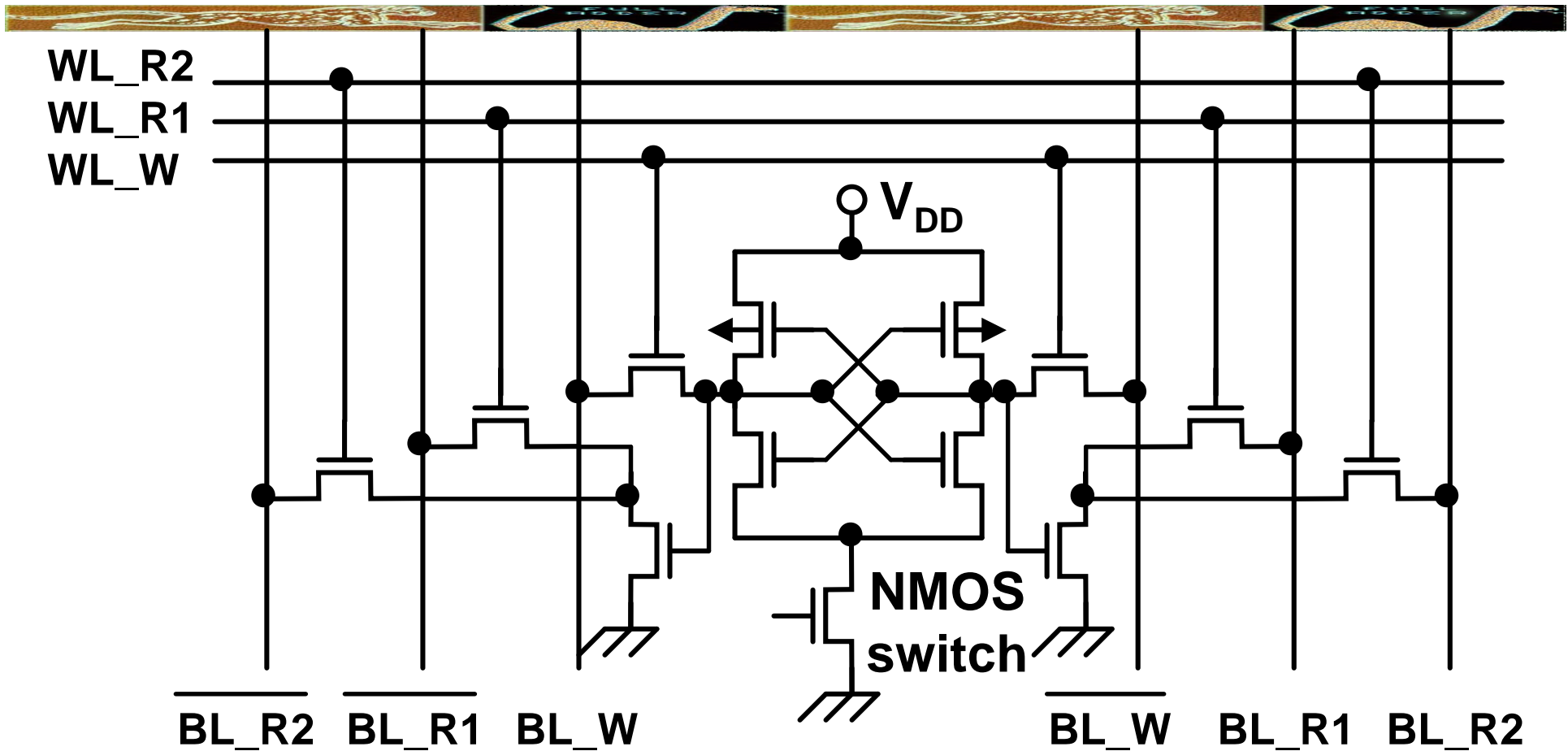


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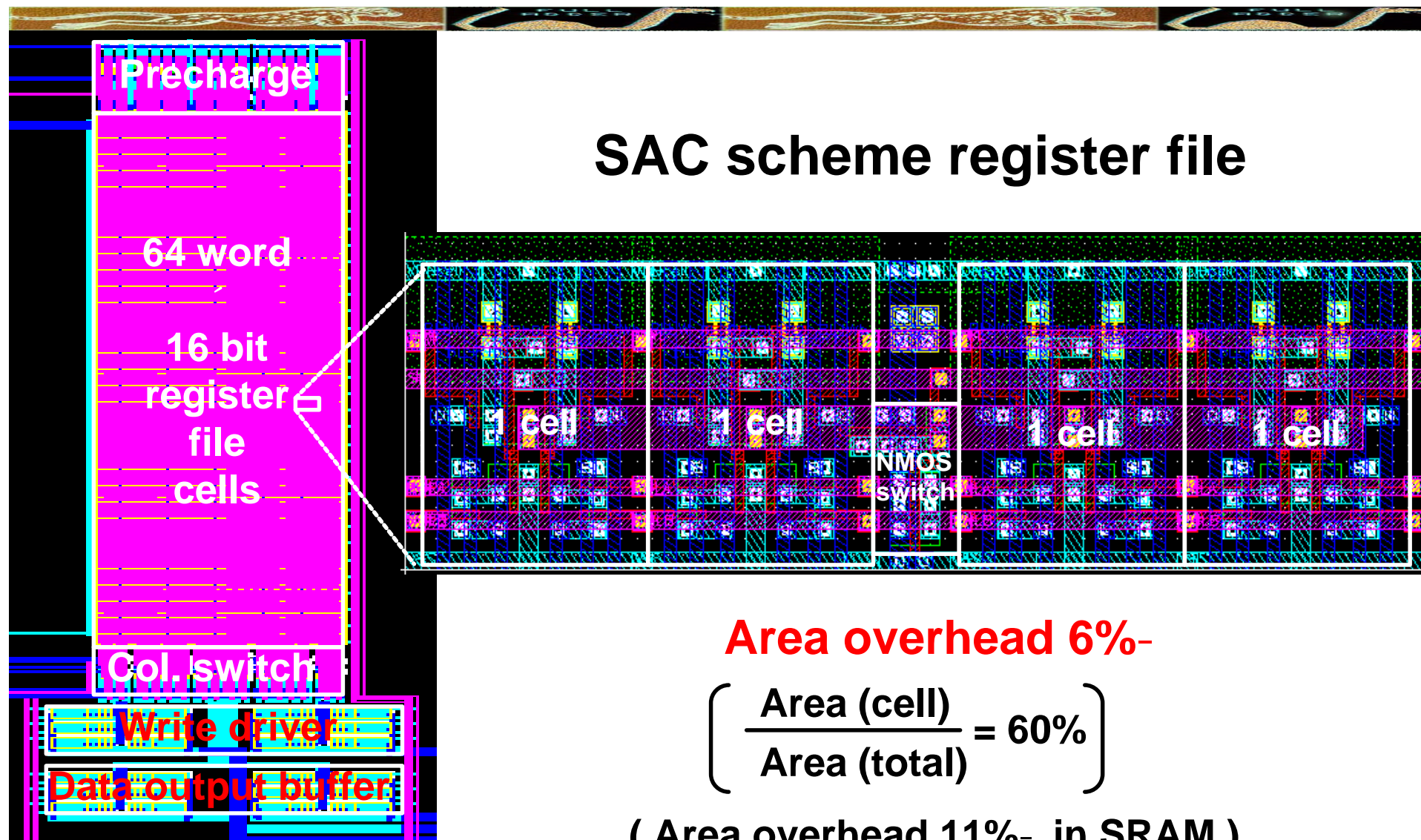
Register file cell with NMOS switch



**Register file cell with NMOS switch
(one write port and two read ports)**

Area overhead is small compared with SRAM

Layout of register file

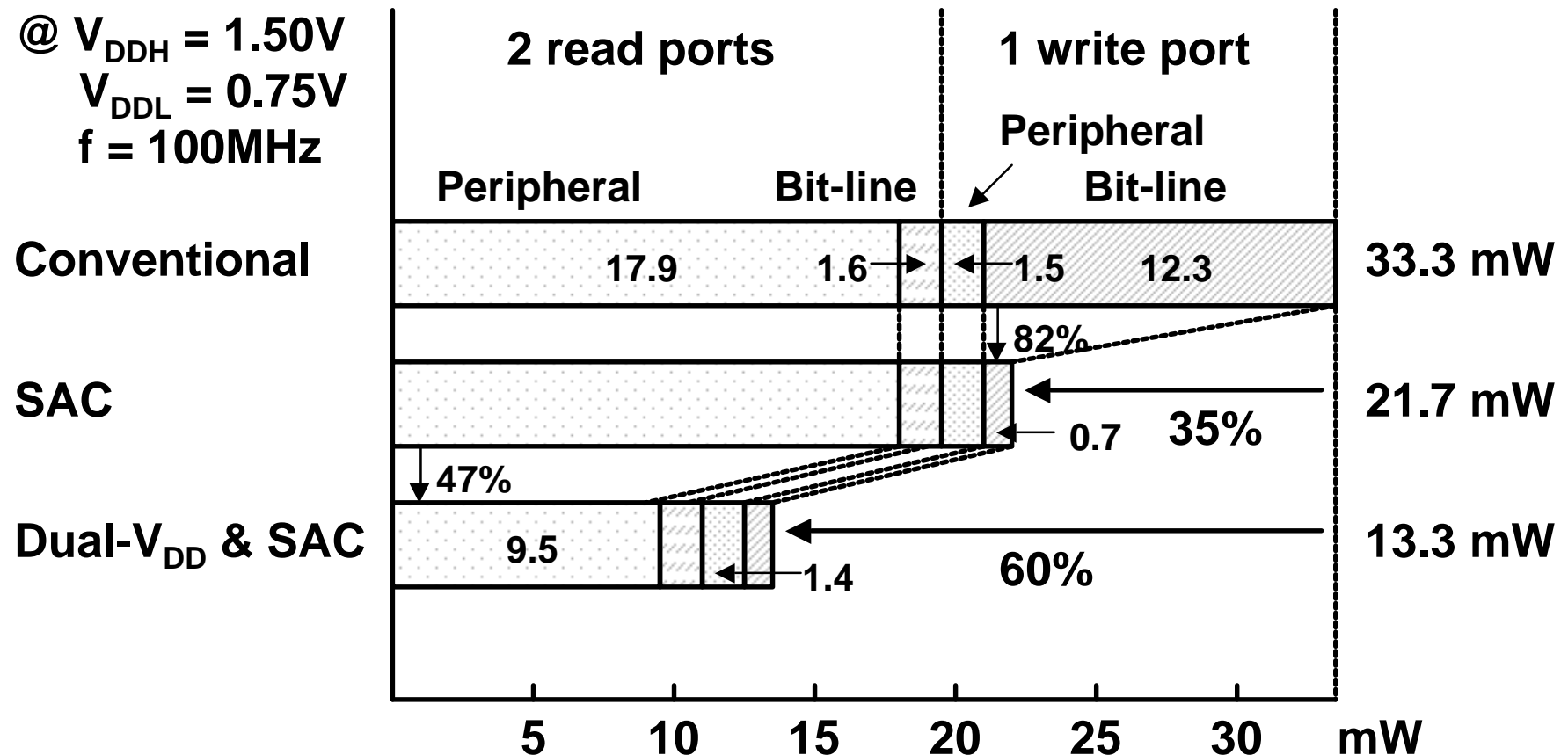


Technology:
0.35-μm CMOS 3-metal (Rohm)

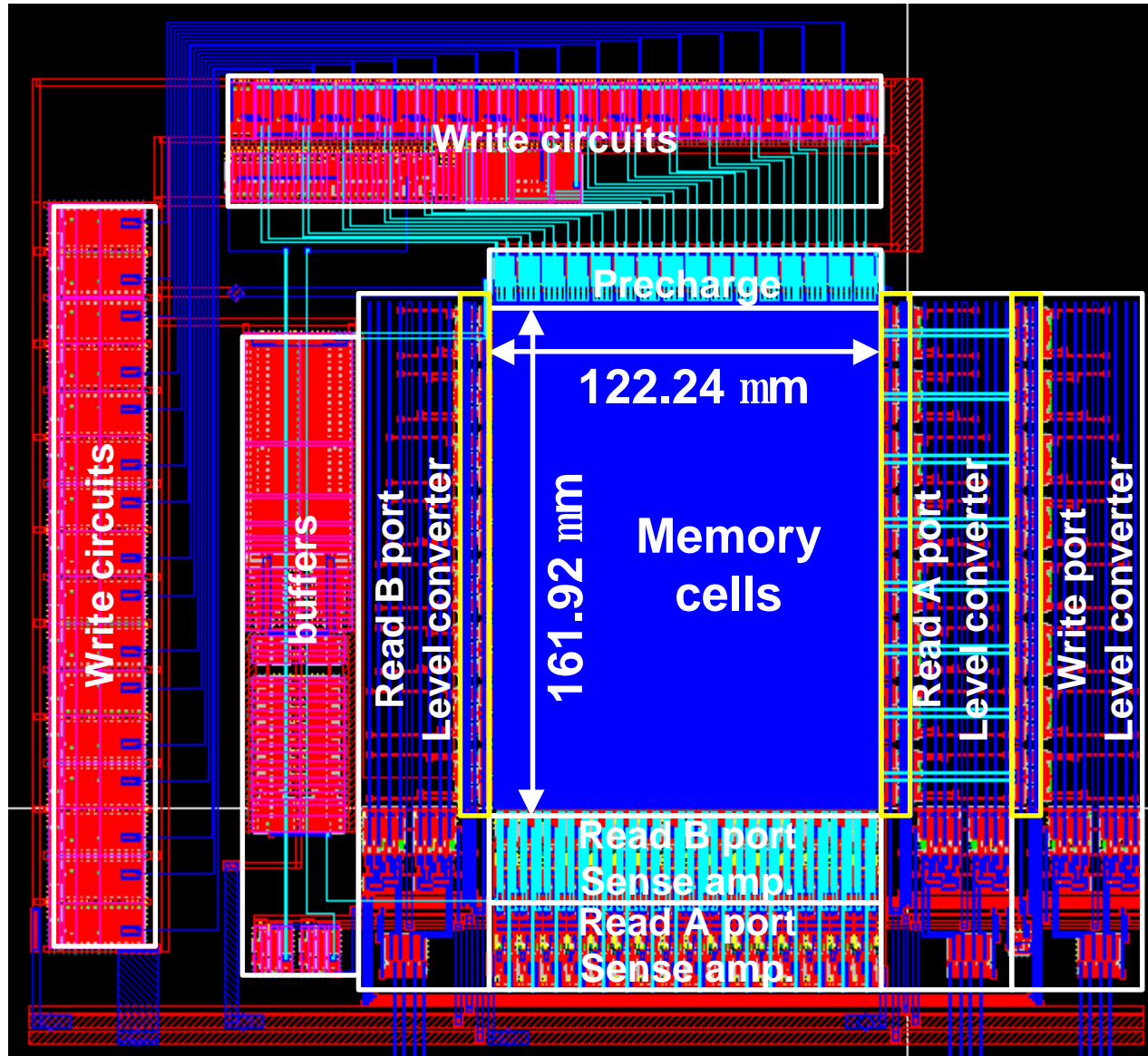
Power consumption of register file

64-word × 256-bit register file

@ $V_{DDH} = 1.50V$
 $V_{DDL} = 0.75V$
 $f = 100MHz$



Layout of 16-word × 16-bit register file With level converter



Technology:
0.25- μ m SOI
3-metal
(NEC)

Summary

Low-power SRAM design

1. Write power saving by SAC scheme

- ③ 81% total write power saving
- ③ 5% delay increase
- ③ 11% area overhead

2. Power saving of peripheral circuits by dual- V_{DD} SRAM architecture

- ③ 54% power saving of peripheral circuits in write cycle
- ③ 90% total write power saving with SAC scheme

3. Application of both schemes to register file

- ③ 60% power saving
- ③ 6% area overhead in SAC scheme